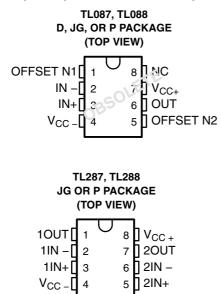
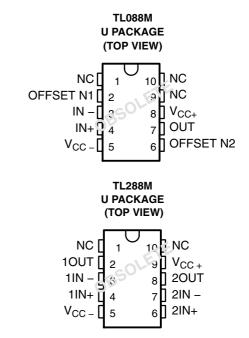
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- Low Input Offset Voltage . . . 0.5 mV Max
- Low Power Consumption
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- High Input Impedance . . . JFET-Input Stage



NC - No internal connection

- Internal Frequency Compensation
- Latch-Up-Free Operation
- High Slew Rate . . . 18 V/μs Typ
- Low Total Harmonic Distortion 0.003% Typ



description/ordering information

These JFET-input operational amplifiers incorporate well-matched high-voltage JFET and bipolar transistors in a monolithic integrated circuit. They feature low input offset voltage, high slew rate, low input bias and offset currents, and low temperature coefficient of input offset voltage. Offset-voltage adjustment is provided for the TL087 and TL088.

The C-suffix devices are characterized for operation from 0° C to 70° C, and the I-suffix devices are characterized for operation from -40° C to 85° C. The M-suffix devices are characterized for operation over the full military temperature range of -55° C to 125° C.

ORDERING INFORMATION

T _A	TYPE	V _{IO} MAX AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	Dual	1 mV	PDIP (P)	Tube of 50	TL288CP	TL288CP

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

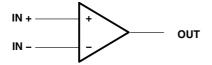


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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symbol (each amplifier)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

		TL088M TL288M	TL087I TL088I TL287I TL288I	TL087C TL088C TL287C TL288C	UNIT	
Supply voltage, VCC+ (see Note 1)		18	18	18	V	
Supply voltage, V _{CC} – (see Note 1)		-18	-18	-18	V	
Differential input voltage (see Note 2)		±30	±30	±30	V	
Input voltage (see Notes 1 and 3)		±15	±15	±15	V	
Input current, I _I (each Input)	±1	±1	±1	mA		
Output current, IO (each output)	±80	±80	±80	mA		
Total V _{CC} + terminal current		160	160	160	mA	
Total V _{CC} - terminal current		-160	-160	-160	mA	
Duration of output short circuit (see Note 4)		Unlimited	Unlimited	Unlimited		
Continuous total dissipation		See Dissipation Rating Table				
Maximum junction temperature, T _J			150	150	°C	
Package thermal impedance, θ _{JA} (see Notes 5 and 6)		85	85	°C/W		
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	JG or U package	300	300	300	°C	
Storage temperature range, T _{stg}	-65 to 150	-65 to 150	-65 to 150	°C		

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-} .
 - 2. Differential voltages are at the noninverting input terminal with respect to the inverting input terminal.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - 4. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is PD = $(T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 7. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 - 8. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is PD = $(T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 9. The package thermal impedance is calculated in accordance with JESD 51-7.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _{A =} 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
JG	1050 mW	8.4 mW/°C	672 mW	546 mW	210 mW
U	675 mW	5.4 mW/°C	432 mW	351 mW	135 mW

TL087, TL088, TL287, TL288 JFET-INPUT OPERATIONAL AMPLIFIERS

The TL087, TL088, and TL287 are obsolete and are no longer supplied.

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recommended operating conditions

		C-SUFFIX		I-SUF	FIX	M-SU	UNIT		
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
V_{CC}	Supply voltage		±5	±5	±5	±5	±5	±15	V
		$V_{CC\pm} = \pm 5 \text{ V}$	-1	4	-1	4	-1	4	.,
V_{IC}	Common-mode input voltage	$V_{CC\pm} = \pm 15 \text{ V}$	-11	11	-11	11	-11	11	V
.,	la antinalla na	$V_{CC\pm} = \pm 5 \text{ V}$	-1	4	-1	4	-1	4	.,,
VI	Input voltage	$V_{CC\pm} = \pm 15 \text{ V}$	-11	11	-11	11	-11	11	V
T _A	Operating free-air temperature		0	70	-40	85	-55	125	°C

operating characteristics $V_{CC}=\pm 15$ V, T_{A} = $25^{\circ}C$

PARAMETER		TEST CONDITIONS		TL088M, TL288M			TL087I, TL087C TL088I, TL088C			UNIT
				MIN	TYP MAX		MIN	TYP	MAX	
SR	Slew rate at unity gain	V _I = 10 V, C _L = 100 pF,	$R_L = 2 k\Omega$, $A_{VD} = 1$		18		8	18		V/μs
t _r	Rise time	V _I = 20 mV,	$R_L = 2 k\Omega$,		55			55		ns
	Overshoot factor	$C_L = 100 pF,$	$A_{VD} = 1$		25			25		%
V_n	Equivalent input noise voltage	$R_S = 100 \Omega$,	f = 1 kHz		19			19		nV/√ Hz

electrical characteristics, $V_{CC\pm} = \pm 15 \text{ V}$

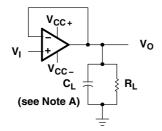
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	PARAMETER	TEST CONDITIONS†		TL088M TL288M		TL087I TL088I TL287I TL288I			TL087C TL088C TL287C TL288C			UNIT	
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
		$R_S = 50 \Omega$,	TL087, TL287					0.1	0.5		0.1	0.5	
	land affect valte as	$V_O = 0$ $T_A = 25^{\circ}C$	TL088, TL288		0.1	3		0.1	1		0.1	1	\ <i>(</i>
V_{IO}	Input offset voltage	$R_S = 50 \Omega$,	TL087, TL287						2			1.5	mV
		$V_O = 0$, $T_A = \text{full range}$	TL088, TL288			6			3			2.5	
α _{VIO}	Temperature coefficient of input offset voltage	$R_S = 50 \Omega$,	T _A = 25°C to MAX		10			8			8		μV/°C
	Input offset current	T _A = 25°C			5			5	100		5	100	pA
I _{IO}	input onset current	$T_A = full range$				25			3			2	nA
I _{IB}	Input bias current [‡]	T _A = 25°C			30			30	200		30	200	pA
		$T_A = full range$				100			20			7	nA
	Common-mode input voltage range	T _A = 25°C		(V _{CC} ₋) + 4		(V _{CC} ₋) +4		(V _{CC} ₋) +4			v		
V_{ICR}													
	voltago rango			(V _{CC+})	-4		(V_{CC+})	-4		(V_{CC+})	-4		
	Maximum-peak-to-peak	$T_A = 25^{\circ}C$,	$R_L = 10 \text{ k}\Omega$	24	27		24	27		24	27		
V _{O(PP)}	output voltage swing	T _A = full range	$R_L \ge 10 \text{ k}\Omega$	24			24			24			V
	output voltage owing	TA = Tull Tallige	$R_L \ge 2 k\Omega$	20			20			20			
		$R_L \ge 2 k\Omega$,	$V_O = \pm 10 \text{ V},$	50	105		50	105		50	105		
A _{VD}	Large-signal differential	T _A = 25°C											V/mV
1.40	voltage amplification	$R_L \ge 2 k\Omega$,	$V_{O} = \pm 10 \text{ V},$	25			25			25			.,
		$T_A = full range$											
B ₁	Unity-gain bandwidth	T _A = 25°C			3			3			3		MHz
rį	Input resistance	T _A = 25°C			10 ¹²			10 ¹²			10 ¹²		Ω
CMRR	Common-mode rejection	_	$V_O = 0 V$,	80	93		80	93		80	93		dB
	ratio	$V_{IC} = V_{ICR}$ min,											
l.	Supply voltage rejection	$R_S = 50 \Omega$,											
k _{SVR}	ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC\pm} = \pm 9 \text{ V to}$ $T_A = 25^{\circ}\text{C}$	±15 V,	80	99		80	80 99		80	99		dB
Icc	Supply current	No load,	V _O = 0 V,		26	2.8		2.6	2.8		2.6	2.8	mA
.00	(per amplifier)	$T_A = 25^{\circ}C$				5		,	5			5	

[†] All characteristics are measured under open–loop conditions with zero common-mode input voltage, unless otherwise specified. Full range for T_A is –55°C to 125°C for TL_88M; –40°C to 85°C for TL_8_I; and 0°C to 70°C for TL_8_C.

[‡] Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

PARAMETER MEASUREMENT INFORMATION



NOTE A: C_L includes fixture capacitance.

Figure 1. Slew Rate, Rise/Fall Time, and Overshoot Test Circuit

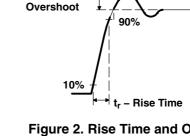


Figure 2. Rise Time and Overshoot Waveform

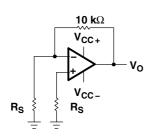
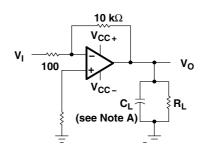


Figure 3. Noise Voltage Test Circuit



NOTE A: C_L includes fixture capacitance.

Figure 4. Unity-Gain Brandwidth and Phase Margin Test Circuit

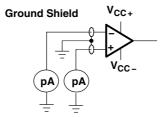


Figure 5. Input Bias and Offset Current Test Circuit

TL087, TL088, TL287, TL288 JFET-INPUT OPERATIONAL AMPLIFIERS

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typical values

Typical values as presented in this data sheet represent the median (50% point) of device parametric performance.

input bias and offset current

At the picoamp bias current level typical of these JFET operational amplifiers, accurate measurement of the bias current becomes difficult. Not only does this measurement require a picoammeter, but test socket leakages can easily exceed the actual device bias currents. To accurately measure these small currents, Texas Instruments uses a two-step process. The socket leakage is measured using picoammeters with bias voltages applied, but with no device in the socket. The device then is inserted in the socket and a second test that measures both the socket leakage and the device input bias current is performed. The two measurements then are subtracted algebraically to determine the bias current of the device.



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TYPICAL CHARACTERISTICS

table of graphs

			FIGURE
αVIO	Temperature coefficient of input offset voltage	Distribution	6, 7
I _{IO}	Input offset current	vs Temperature	8
I _{IB}	Input bias current	vs V _{IC} vs Temperature	9 8
VI	Common-mode input voltage range limits	vs V _{CC} vs Temperature	10 11
V _{ID}	Differential input voltage	vs Output voltage	12
V _{OM}	Maximum peak output voltage swing	vs V _{CC} vs Output current vs Frequency vs Temperature	13 17 14, 15, 16 18
A _{VD}	Differential voltage amplification	vs R _L vs Frequency vs Temperature	19 20 21
z _o	Output impedance	vs Frequency	24
CMRR	Common-mode rejection ratio	vs Frequency vs Temperature	22 23
k _{SVR}	Supply-voltage rejection ratio	vs Temperature	25
I _{OS}	Short-circuit output current	vs V _{CC} vs Time vs Temperature	26 27 28
I _{CC}	Supply current	vs V _{CC} vs Temperature	29 30
SR	Slew rate	vs R _L vs Temperature	31 32
	Overshoot factor	vs C _L	33
V _n	Equivalent input noise voltage	vs Frequency	34
THD	Total harmonic distortion	vs Frequency	35
B ₁	Unity-gain bandwidth	vs V _{CC} vs Temperature	36 37
фm	Phase margin	vs V _{CC} vs C _L vs Temperature	38 39 40
	Phase shift	vs Frequency	20
	Pulse response	Small-signal Large-signal	41 42



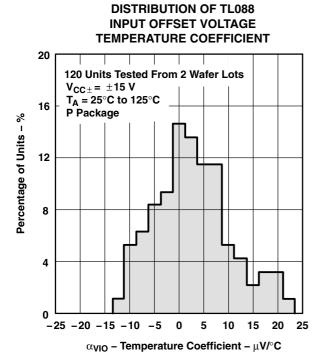
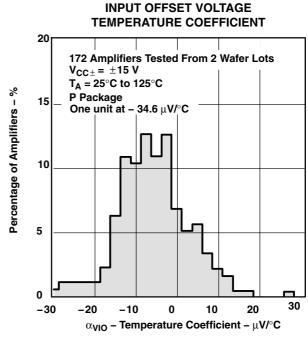


Figure 6



DISTRIBUTION OF TL288

Figure 7



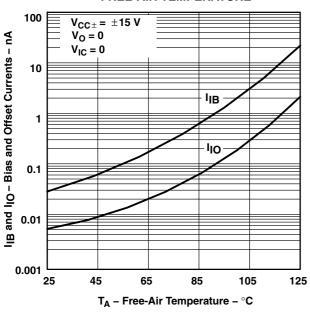


Figure 8

INPUT BIAS CURRENT vs COMMON-MODE INPUT VOLTAGE

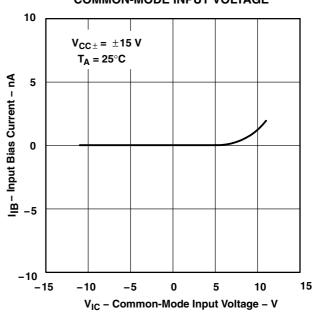
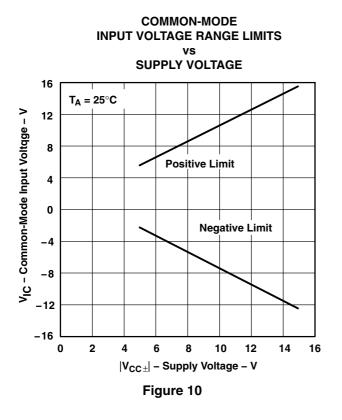


Figure 9

[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.





COMMON-MODE
INPUT VOLTAGE RANGE LIMITS
vs



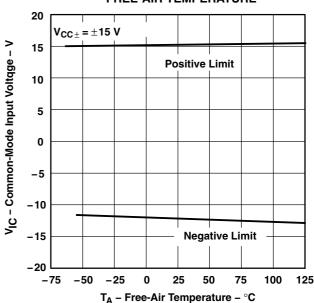


Figure 11



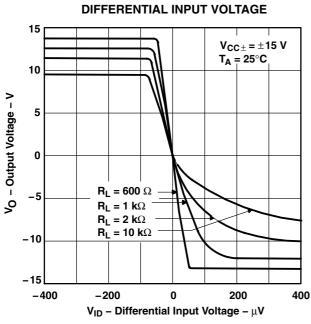


Figure 12

MAXIMUM PEAK OUTPUT VOLTAGE

vs

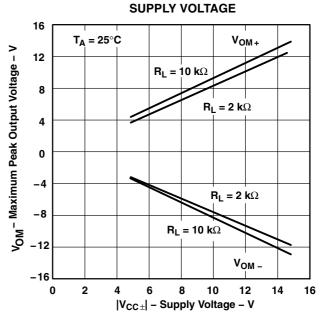


Figure 13

[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE

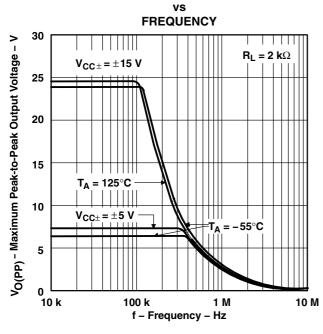


Figure 14

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE

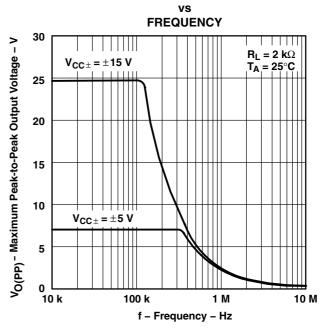
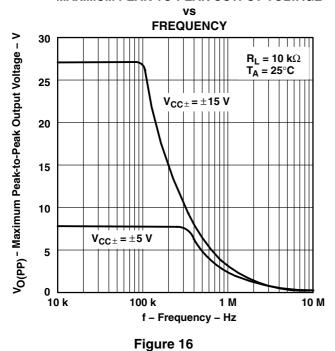
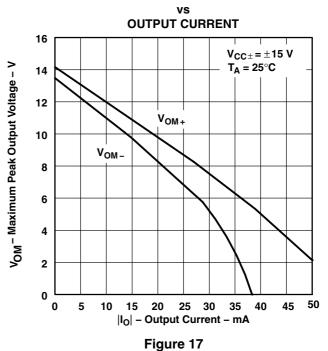


Figure 15

MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE



MAXIMUM PEAK OUTPUT VOLTAGE

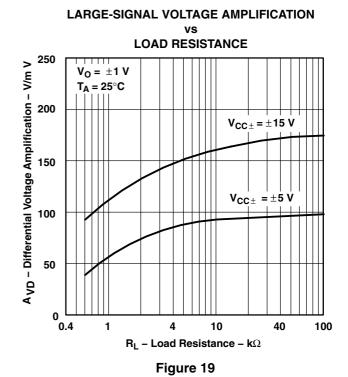


[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



MAXIMUM PEAK OUTPUT VOLTAGE FREE-AIR TEMPERATURE 16 $R_L = 10 \text{ k}\Omega$ V_{OM} - Maximum Peak Output Voltage - V 12 $R_L = 2 k\Omega$ V_{OM+} 8 4 $V_{CC\pm} = \pm 15 \text{ V}$ 0 -4 -8 V_{OM} $R_L = 2 k\Omega$ -12 $R_L = 10 \text{ k}\Omega$ -16 -75 -50 25 50 75 100 125 T_A - Free-Air Temperature - °C

Figure 18



LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

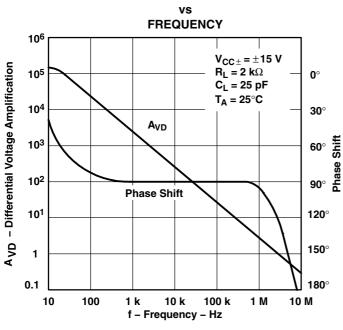


Figure 20

LARGE-SIGNAL VOLTAGE AMPLIFICATION

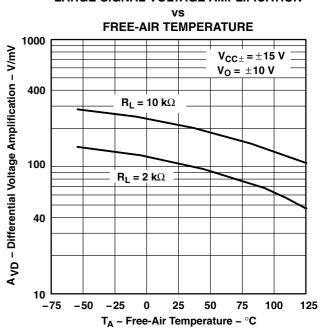


Figure 21

[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



COMMON-MODE REJECTION RATIO FREQUENCY 100 CMRR - Common-Mode Rejection Ratio - dB $V_{CC\pm} = \pm 15 \text{ V}$ 90 $T_A = 25^{\circ}C$ 80 70 60 50 40 30 20 10 0 100 10 M 10 10 k 100 k 1 M 1 k f - Frequency - Hz

Figure 22

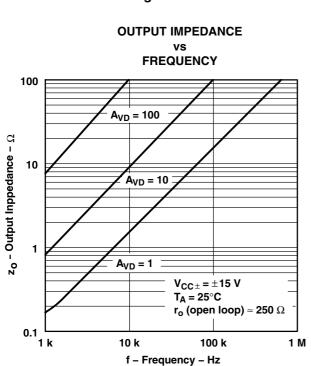


Figure 24

COMMON-MODE REJECTION RATIO vs FREE-AIR TEMPERATURE

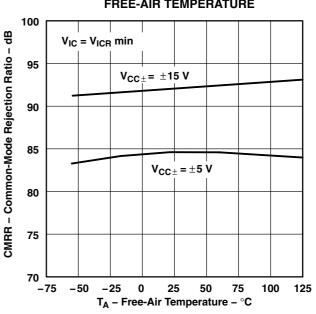


Figure 23

SUPPLY-VOLTAGE REJECTION RATIO vs

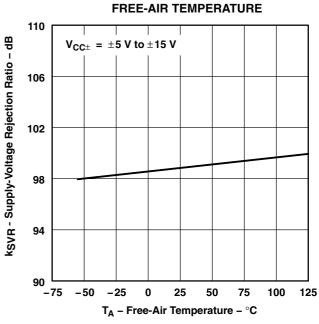
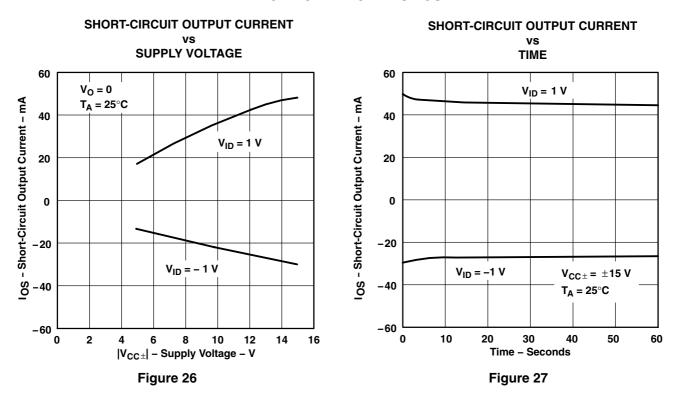


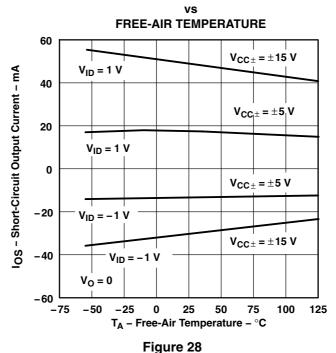
Figure 25

[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



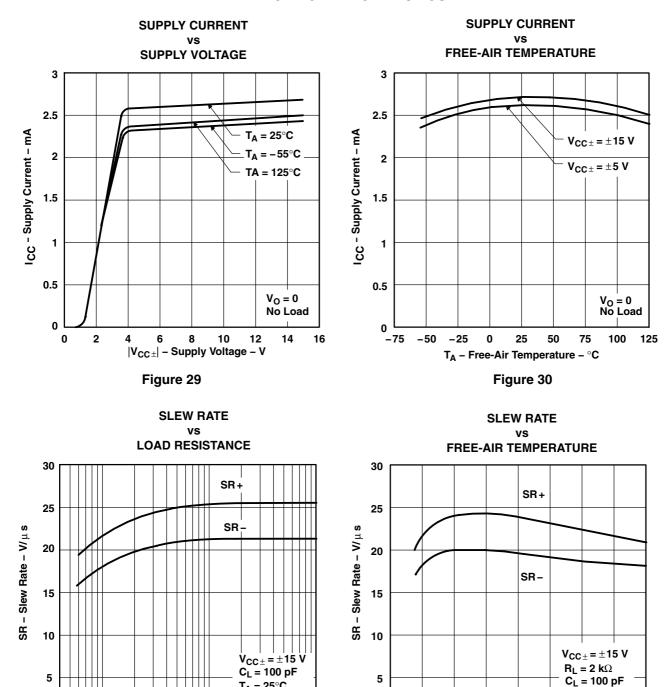


SHORT-CIRCUIT OUTPUT CURRENT



[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.





100

T_A = 25°C

4

Figure 31

10

 R_L – Load Resistance – $k\Omega$

See Figure 1

40



-75

-50

-25

25

T_A - Free-Air Temperature - °C

Figure 32

50

See Figure 1

100

125

75

0 0.4

[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.

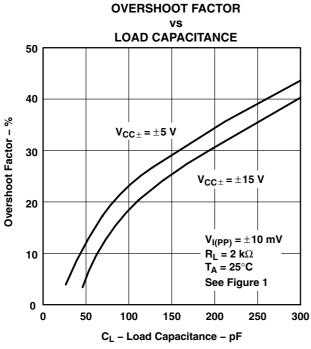


Figure 33

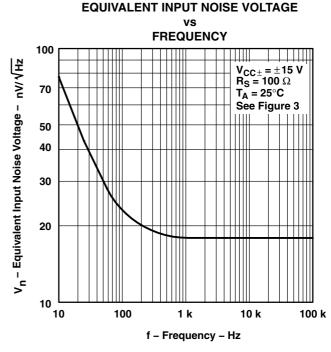
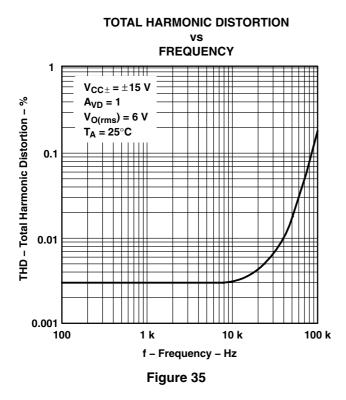
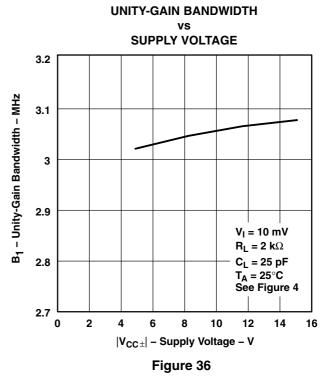


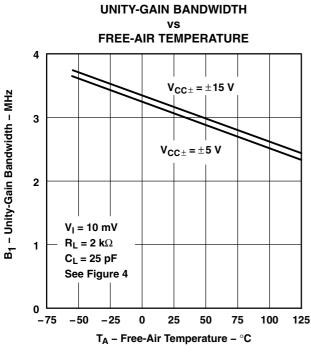
Figure 34





[†] Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.





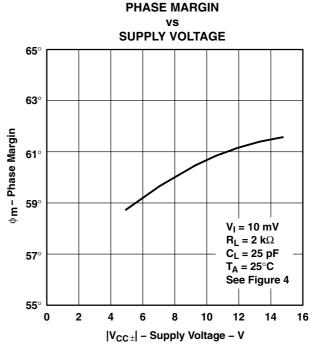
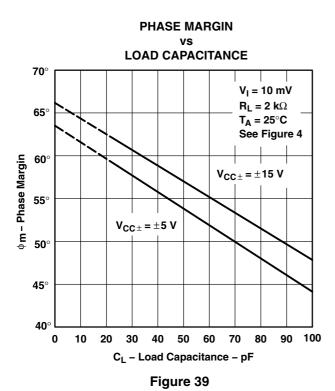
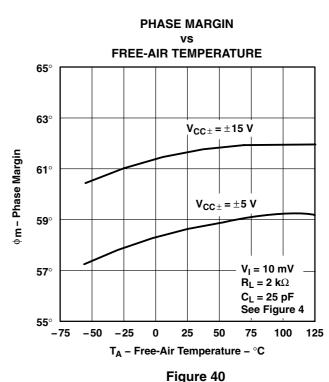


Figure 37







† Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.



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TYPICAL CHARACTERISTICS

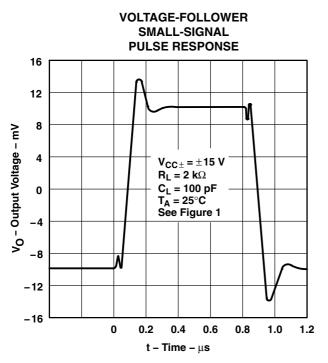


Figure 41

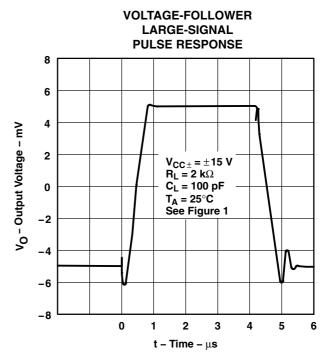


Figure 42

TYPICAL APPLICATION DATA

output characteristics

All operating characteristics are specified with 100-pF load capacitance. These amplifiers will drive higher capacitive loads; however, as the load capacitance increases, the resulting response pole occurs at lower frequencies, causing ringing, peaking, or even oscillation. The value of the load capacitance at which oscillation occurs varies with production lots. If an application appears to be sensitive to oscillation due to load capacitance, adding a small resistance in series with the load should alleviate the problem. Capacitive loads of 1000 pF, and larger, may be driven if enough resistance is added in series with the output (see Figure 43).

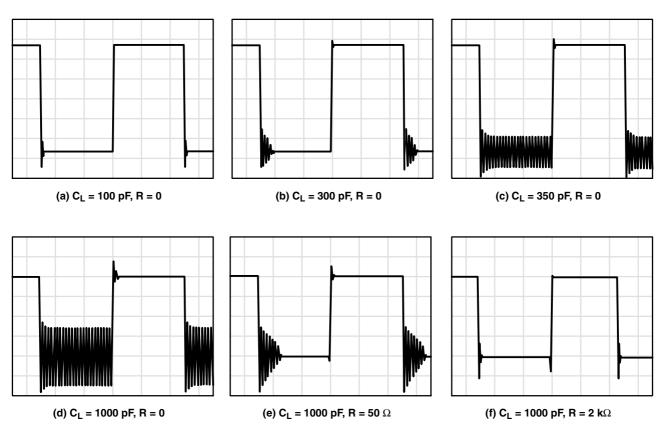


Figure 43. Effect of Capacitive Loads

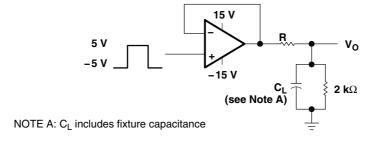


Figure 44. Test Circuit for Output Characteristics



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TYPICAL APPLICATION DATA

input characteristics

These amplifiers are specified with a minimum and a maximum input voltage that, if exceeded at either input, could cause the device to malfunction.

Because of the extremely high input impedance and resulting low bias current requirements, these amplifiers are well suited for low-level signal processing; however, leakage currents on printed circuit boards and sockets easily can exceed bias current requirements and cause degradation in system performance. It is good practice to include guard rings around inputs (see Figure 45). These guards should be driven from a low-impedance source at the same voltage level as the common-mode input.

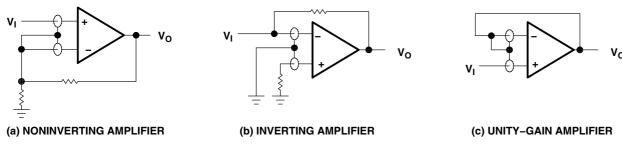


Figure 45. Use of Guard Rings

noise performance

The noise specifications in operational amplifier circuits are greatly dependent on the current in the first-stage differential amplifier. The low input bias current requirements of these amplifiers result in a very low current noise. This feature makes the devices especially favorable over bipolar devices when using values of circuit impedance greater than 50 k Ω .





9-Feb-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL288CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL288CPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

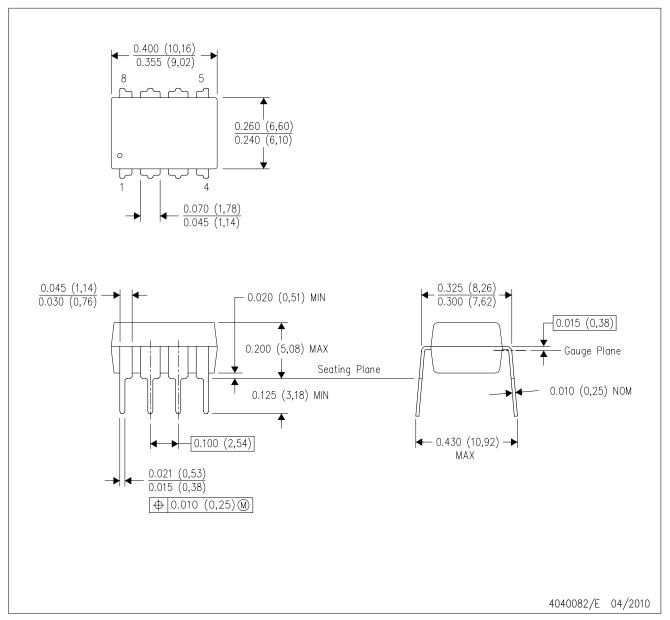
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.

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